

Technology Roadmap

Base Materials		Standard (At Now)	Advanced (2015)
		Rigid	Mixed Di-Electric
		FR2 CEM 1 FR4 Standard / Halogen Free FR4 Tg High / Tg. Variants	Low Loss Materials
		Flex - PI / Polyester	COB
		Flex-Rigid	
		Aluminium	Aluminium / Copper mixed materials
Layer Count		26L	Trialling 40L
Min Material Thickness			
FR4		0.075mm	0.050mm
PI		0,025mm	0,015mm
MAX PCB Thickness		7.40mm	9.50mm
MAX PCB Dimension (Finished Length)		1250mm	1500mm
PCB Design Features			
Minimum Track (35um Cu.)		0.075mm	0.050mm
Minimum Space		0.075mm	0.050mm
Minimum Hole size (Drilled)			
Mechanical		0.20mm	0.15mm
Laser		0.10mm	0.050mm
Through		Y	
Laser Drilled Via		Y	
Laser Resin Filled Via		Y	
Laser Copper filled Via		Y	
Laser Copper filled Flat Via		Y	
Laser Paste Filled via		N	Y
HDI Construction		2+X +2	1+2+X+2+1
Surface Finish		Imm Gold Imm Silver Imm Tin OSP ENIG Imm. Pd. Au. Imm. Pd. Ag. HAL LF HAL	
Solder Mask Dam		0.075mm	0.050mm
Layer to Layer to registration		0.10mm	0.075mm
Edge of feature to Edge of Hole		0.30mm	0.20mm
Copper Weight Max (Finish)			
Internal		105um	140um
Outer		210um	